ADG5233 and ADG5234
LFCSP Redesign Qualification

QUALIFICATION RESULT			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULT**
Solder Heat Resistance Test (SHR)*	JEDEC/IPC *J-STD-020*	1 x 30	PASS
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	1 x 77	PASS
Electrostatic Discharge *Human Body Model*	ESDA/JEDEC *JS-001*	3/voltage	PASS ±1500V
Electrostatic Discharge *Machine Body Model*	JEDEC *JESD22-A115*	3/voltage	PASS ±400V
Electrostatic Discharge *Field-Induced Charged Device Model*	JEDEC *JESD22-C101*	3/voltage	PASS ±1250V

*Preconditioned per JEDEC/IPC J-STD-020

ADG5233 and ADG5234 LFCSP Redesign
Resulting in Datasheet Specification Changes

4x4mm LFCSP at STATS ChipPAC China

QUALIFICATION RESULT			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULT**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 77	PASS
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	3 x 77	PASS
Autoclave (AC)*	JEDEC *JESD22-A102*	3 x 77	PASS
High Temperature Storage (HTS)	JEDEC *JESD22-A103*	1 x 77	PASS

*Preconditioned per JEDEC/IPC J-STD-020

2um HV CMOS Process at AD Limerick

QUALIFICATION RESULT			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULT**
High Temperature Operating Life (HTOL)*	JEDEC *JESD22-A108*	9 x 77	PASS
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	9 x 77	PASS
High Temperature Storage (HTS)	JEDEC *JESD22-A103*	3 x 49	PASS

*Preconditioned per JEDEC/IPC J-STD-020